Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Currently amended): A method for manufacturing a ceramic circuit board, comprising the steps of:

preparing a ceramic substrate having a through hole, a metal column with brazing material, and at least two pieces of metal circuit plates, said metal column with brazing material being made longer relative to a thickness of the ceramic substrate, by coating both ends of a metal column which is shorter relative to the thickness of the ceramic substrate, with a brazing material;

arranging the metal column with brazing material within the through hole of the ceramic substrate, so that a space defining a cavity is ~~defined along the entire length of the metal column,~~ secured between an inner wall surface of the through hole and an outer wall surface of the metal column, and arranging the metal circuit plates on both surfaces of the ceramic substrate in such a way as to stop up the through hole, wherein the cavity is free from material; and

bonding, after melting the brazing material by heating, the metal column and the metal circuit plates together via the molten brazing material.

3-4. (Canceled)

5. (Original): The method for manufacturing the ceramic circuit board of claim 2,

wherein the metal circuit plate is made of copper or aluminum.

6. (Original): The method for manufacturing the ceramic circuit board of claim 2,

wherein the metal column is made of copper or aluminum.

7. (Canceled)

8. (Previously presented): The method for manufacturing the ceramic circuit board of claim 2,

wherein a distance between an inner wall surface of the through hole and an outer wall surface of the metal column is in a range of 30 to 200 μm.

9-15. (Canceled).

16. (Previously presented): The method for manufacturing the ceramic circuit board of claim 2,

wherein a length of the metal column is 0 to 150 μm shorter relative to a thickness of the ceramic substrate and a length of the metal column with brazing material is 40 to 140 μm longer relative to the thickness of the ceramic substrate.